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#### 捷多邦,专业PCB打样工厂。24小时机争出货 ISO 9001 CERTIFIED BY DSCC



#### M.S.KENNEDY CORP.

4707 Dey Road Liverpool, N.Y. 13088

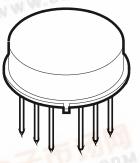
#### FEATURES:

- Industry Wide LH0033/EL2005 Replacement
- · Low Input Offset 2mV
- Low Input Offset Drift 25µV/°C
- FET Input, Low Input Current 50pA
- High Slew Rate 1500V/µS
- Wide Bandwidth 140MHz
- High Output Current ±100mA
- Available to DSCC SMD 5962-80014

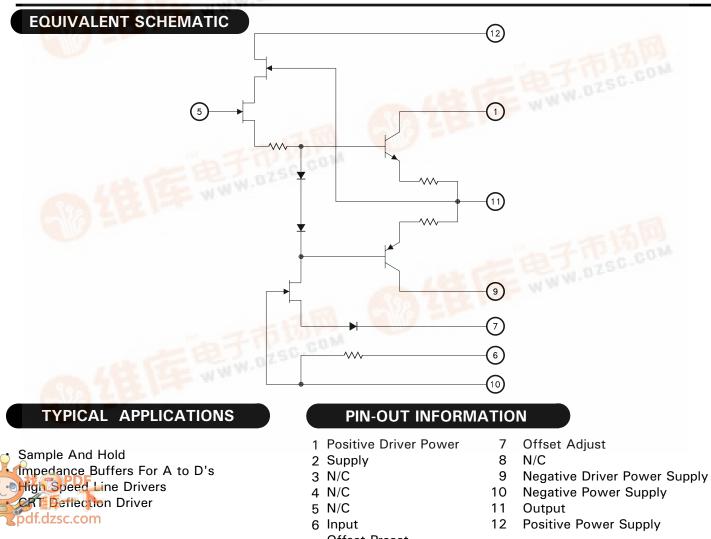
#### **DESCRIPTION:**

MIL-PRF-38534 CERTIFIED

(315) 701-6751



The MSK 0033(B) is a high speed, wide bandwidth voltage follower/buffer amplifier that is pin compatible with all other 0033 designs. The FET input is cascaded to force the input characteristics to remain constant over the full input voltage range. Significantly improved performance in sample and hold circuits is achieved since the DC bias current remains constant with input voltage. The FET input also makes the MSK 0033 very accurate since it produces extremely low input bias current, input offset voltage and input offset voltage drift specifications. Transistion times in the range of 2.5 nS make the MSK 0033 fast enough for most high speed voltage follower/buffer amplifier applications.



# **ABSOLUTE MAXIMUM RATINGS**

$\pm V$ cc	Supply Voltage±20V
lout	Output Current ±120mA
Vin	Differential Input Voltage
Tc	Case Operating Temperature
	(MSK 0033B)
	(MSK 0033)

Тsт	Storage Temperature Range -65°C to +150°C
TLD	Lead Temperature Range
	(10 Seconds)
ТJ	Junction Temperature
Rтн	Thermal Resistance
	Junction to Case
	Output Devices Only

# **ELECTRICAL SPECIFICATIONS**

Parameter	Test Conditions	Group A	MSK 0033B			MSK 0033			
Falameter	rest conditions		Min.	Тур.	Max.	Min.	Тур.	Max.	Units
STATIC									
Supply Voltage Range ③ ⑧		-	±10	±15	±18	±10	±15	±18	V
Quiescent Current	VIN=OV	1	-	±19	±22	-	±19	±25	mA
INPUT									
Offset Voltage	Short Pin 6 to Pin 7 VIN = 0V	1	-	±2.0	±10	-	±5	±15	mV
Offset Voltage Drift	Short Pin 6 to Pin 7 VIN = 0V	2,3	-	± 25	±250	-	-	-	µV/°C
Offset Adjust Pin 6	$B = open RPOT = 200\Omega$ From Pin 7 to Pin 9	1,2,3	Adjust to Zero Adjust to Zero		lero	mV			
Input Bias Current (9)	Vcm=0V	1	-	±50	±100	-	±50	±500	pА
	Either Input	2,3	-	±2	±10	-	±2	-	nA
Input Impedance ③	F = DC	-	-	1012	-	-	1012	-	Ω
Power Supply Rejection Ratio ② ±10V≤Vs≤±20V		-	65	75	-	60	75	-	dB
Input Noise Density ③	F=10Hz to 1KHz	-	-	1.5	-	-	1.5	-	µVRMS
Input Noise Voltage ③	F = 1KHz	-	-	40	-	-	40	-	nV/√Hz
OUTPUT									
Output Voltage Swing	$V_{IN}=\pm14V\ R_L=1K\Omega$	4	±12	±12.5	-	±12	±12.5	-	V
Output Current	$V_{IN}=\pm10.5V\ R_L=100\Omega$	4	±90	±110	-	±90	±110	-	mA
Settling Time to 1% ②③	2V step	-	-	25	-	-	25	-	nS
Bandwidth (-3dB) ③	$V_{IN} = 1 V_{RMS} R_L = 1 K \Omega$	-	-	140	-	-	140	-	MHz
TRANSFER CHARACTERISTICS	;								
Slew Rate	$Vout = \pm 10V$	4	1000	1500	-	1000	1500	-	V/µS
Voltage Gain	$Rs = 100\Omega$ Vin = 1Vrms F = 1KHz	4	0.97	0.99	-	0.95	0.98	-	V/V

## NOTES:

- Unless otherwise specified ±VCC = ±15 VDC.
  Measured within a high speed amplifier feedback loop.
  Devices shall be capable of meeting the parameter, but need not be tested. Typical parameters are for reference only.
  Industrial grade devices shall be tested to subgroups 1 and 4 unless otherwise specified.
  Military grade devices ('B' suffix) shall be 100% tested to subgroups 1,2,3 and 4.
  Subgroup 5 and 6 testing available upon request.
  Subgroup 1,4 TA = Tc = +25 °C
  Subgroup 2,5 TA = Tc = +125 °C

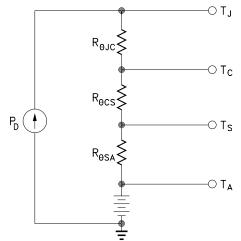
- Subgroup 2,5  $T_A = T_C = +125 \,^{o}C$
- Subgroup 3,6  $T_A = T_C = -55 \circ C$
- B Electrical specifications are derated for power supply voltages other than  $\pm 15$  VDC.
- (9) Measurement made 0.5 seconds after application of power. Actual DC continuous test limit is 2.5 nA at 25°C

### **APPLICATION NOTES**

## HEAT SINKING

To determine if a heat sink is necessary for your application and if so, what type, refer to the thermal model and governing equation below.

#### Thermal Model:



#### Governing Equation:

 $T_J = P_D x (R_{\theta JC} + R_{\theta CS} + R_{\theta SA}) + T_A$ 

#### Where

T<sub>J</sub> = Junction Temperature

- PD = Total Power Dissipation
- $R_{\theta JC}$  = Junction to Case Thermal Resistance
- $R_{\theta CS}$  = Case to Heat Sink Thermal Resistance
- $R_{\theta SA}$  = Heat Sink to Ambient Thermal Resistance
- Tc = Case Temperature
- TA = Ambient Temperature
- Ts = Sink Temperature

#### Example:

This example demonstrates a worst case analysis for the buffer output stage. This occurs when the output voltage is 1/2 the power supply voltage. Under this condition, maximum power transfer occurs and the output is under maximum stress.

#### Conditions:

For a worst case analysis we will treat the  $\pm 8Vp$  sine wave as an 8 VDC output voltage.

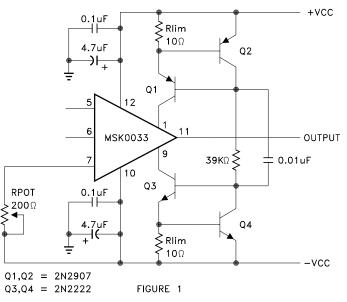
- 1.) Find Driver Power Dissipation
  - PD = (VCC-VO) (VO/RL)
  - = (16V-8V) (8V/100 $\Omega$ )
    - = 640 mW
- 2.) For conservative design, set  $T_J = +125 \,^{\circ}C$  Max.
- 3.) For this example, worst case  $TA = +80^{\circ}C$
- 4.)  $R_{\theta JC} = 65^{\circ}C/W$  from MSK 0033B Data Sheet
- 5.)  $R_{\theta}CS = 0.15^{\circ}C/W$  for most thermal greases
- 6) Rearrange governing equation to solve for Resa

- $\begin{array}{l} {\sf R}_{\theta {\sf S}{\sf A}} \ = \ (({\sf T}_{\sf J} \ \ {\sf T}_{\sf A})/{\sf P}_{\sf D}) \ \ ({\sf R}_{\theta {\sf J}{\sf C}}) \ \ ({\sf R}_{\theta {\sf C}{\sf S}}) \\ \ = \ ((125\,^{\circ}{\sf C}\ \ 80\,^{\circ}{\sf C})\ / \ .64{\sf W}) \ \ 65\,^{\circ}{\sf C}/{\sf W} \ \ .15\,^{\circ}{\sf C}/{\sf W} \\ \ = \ 70.3 \ \ 65.15 \end{array}$ 
  - $= 5.2^{\circ}C/W$

The heat sink in this example must have a thermal resistance of no more than  $5.2^{\circ}$ C/W to maintain a junction temperature of no more than  $+125^{\circ}$ C.

## OFFSET VOLTAGE ADJUST

See Figure 1. To externally null the offset voltage, connect a 200 $\Omega$  potentiometer between Pins 7 and 10 and leave Pin 6 open. If offset null is not necessary, short Pin 6 to Pin 7 and remove the 200 $\Omega$  potentiometer. Do not connect Pin 7 to - Vcc.



#### CURRENT LIMITING

+

See Figure 1. If no current limit is required, short Pin 1 to Pin 12 and Pin 9 to Pin 10 and delete Q1 thru Q4 connections. Q1 through Q4 and the Rlim resistors form a current source current limit scheme and current limit resistor values can be calculated as follows:

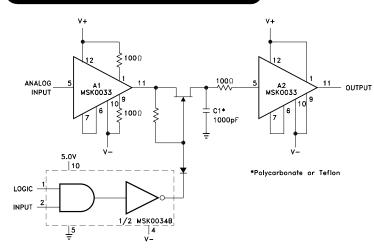
$$\operatorname{Rlim} \cong \frac{\operatorname{Vbe}}{\operatorname{Isc}} \qquad -\operatorname{Rlim} \cong \frac{\operatorname{Vbe}}{\operatorname{Isc}}$$

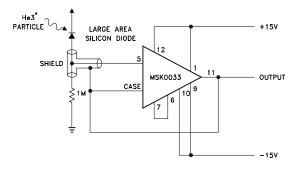
Since current limit is directly proportional to the base-emitter voltage drop of the 2N2222's and 2N2907's in the current limit scheme, the current limit value will change slightly with ambient temperature changes. The base-emitter voltage drop will decrease as temperature increases causing the actual current limit point to decrease.

#### POWER SUPPLY BYPASSING

Both the negative and the positive power supplies must be effectively decoupled with a high and low frequency bypass circuit to avoid power supply induced oscillation. An effective decoupling scheme consists of a 0.1 microfarad ceramic capacitor in parallel with a 4.7 microfarad tantalum capacitor from each power supply pin to ground.

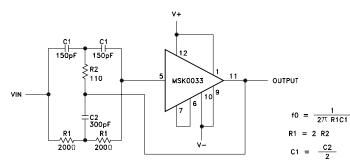
## **TYPICAL APPLICATIONS**



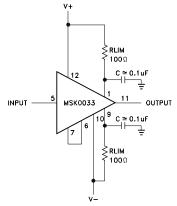


NUCLEAR PARTICLE DETECTOR

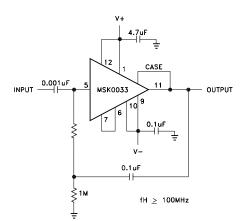
HIGH SPEED SAMPLE AND HOLD



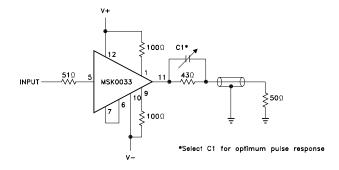




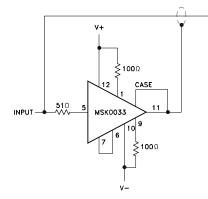
MSK0033 USING RESISTOR CURRENT LIMITING

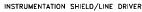


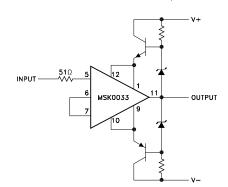




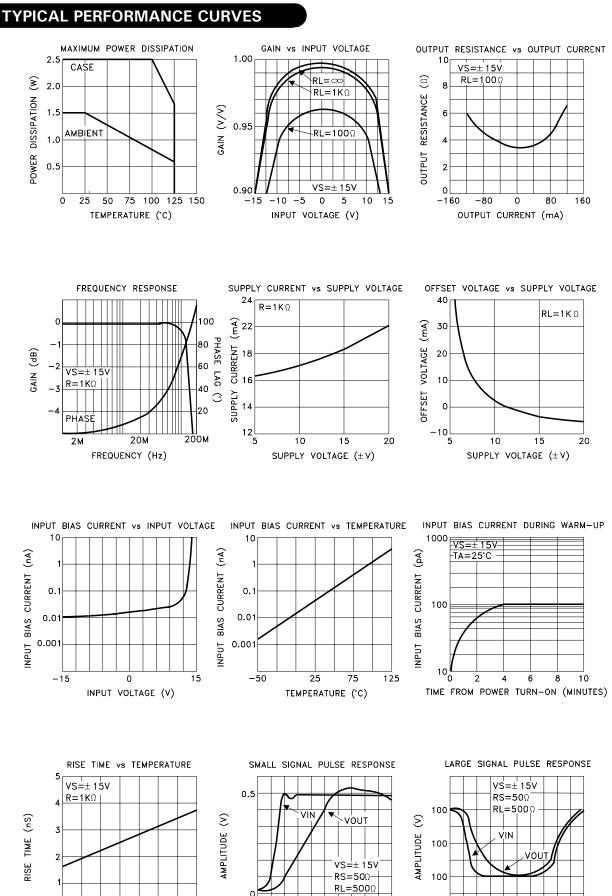
COAXIAL CABLE DRIVER







BOOTSTRAPPED SUPPLIES FOR HIGH VOLTAGE APPLICATIONS



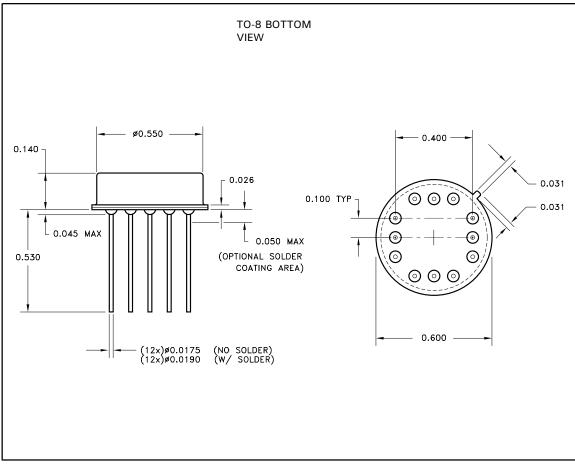
TIME (nS)

TEMPERATURE (°C)

-50

TIME (nS)

# MECHANICAL SPECIFICATIONS



ALL DIMENSIONS ARE ±0.010 INCHES UNLESS OTHERWISE LABELED

# **ORDERING INFORMATION**

Part Number	Screening Level
MSK0033	Industrial
MSK0033B	Military-Mil-PRF-38534
8001401ZX	DSCC - SMD

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